

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1-24. (canceled)

25. (currently amended) An electronic package comprising:

a first circuitry component having a top surface;

a second circuitry component over said top surface;

~~an~~ a first insulating ~~insulation~~ layer covering said second circuitry component and said top surface; and

a metal layer on said ~~insulation~~ first insulating layer.

26. (previously presented) The electronic package of claim 25, wherein said first circuitry component comprises a semiconductor chip.

27. (previously presented) The electronic package of claim 25, wherein said second circuitry component comprises a semiconductor chip.

28. (previously presented) The electronic package of claim 25 further comprising a bump between said first and second circuitry components.

29. (currently amended) The electronic package of claim ~~28-25~~ further comprising ;  
~~wherein said insulation~~ a second insulating layer ~~comprises a portion between said first~~  
and second circuitry components and enclosing said bump.

30. (canceled)

31. (currently amended) The electronic package of claim 25 further comprising a via through said ~~insulation~~ first insulating layer and connecting said first circuitry component and said metal layer.

32. (currently amended) The electronic package of claim 25, wherein said ~~insulation~~ first insulating layer has a top surface comprising a first region and a second region, said first region being over said second circuitry component, said second region being not over said second circuitry component, wherein said first and second regions are coplanar.

33. (previously presented) The electronic package of claim 32, wherein said metal layer is on said first and second regions.

34. (currently amended) The electronic package of claim 25 further comprising a first bump over said metal layer.

35. (currently amended) The electronic package of claim 25, wherein said second circuitry component ~~comprising~~ comprises a top surface and a bottom surface facing said top surface of said first circuitry component, said ~~insulation~~ first insulating layer over said top surface of said second circuitry component.

36-44. (canceled)

45. (new) The electronic package of claim 34 further comprising a substrate and a second bump connected to a bottom surface of said substrate, wherein said first bump is connected to a top surface of said substrate.